100% Material Declaration Data Sheet VQ100

Average Weight: 0.5 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					**0.01995**	**3.99%**
	Silicon	7440-21-3	100.00		0.01995	
Die Attach Material					**0.00315**	**0.63%**
	Silver	7440-22-4	78.00		0.002457	
	Epoxy (EP)	Trade Secret	22.00		0.000693	
Mold Compound					**0.32425**	**64.85%**
	Epoxy Resin (EP)	Trade Secret	9.00		0.0291825	
	Phenolic Resin	Trade Secret	7.00		0.0226975	
	Carbon Black	1333-86-4	0.50		0.00162125	
	Silica	60676-86-0	82.50		0.26750625	
	Bismuth	7440-69-9	Max 1.00		0.0032425	
Leadframe					**0.139**	**27.80%**
	Copper	7440-50-8	96.57		0.1342323	
	Nickel	7440-02-0	2.70		0.003753	
	Silicon	7440-21-3	0.58		0.0008062	
	Magnesium	7439-95-4	0.15		0.0002085	
Leadframe Plating					**0.00225**	**0.45%**
	Silver	7440-22-4	100.00		0.00225	
Bond Wire					**0.00355**	**0.71%**
	Gold	7440-57-5	100.00		0.00355	
Ext. Plating					**0.00785**	**1.57%**
	Tin	7440-31-5	85.00		0.0066725	
	Lead	7439-92-1	15.00		0.0011775	

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Xilinx believes this environmental information to be correct, but cannot guarantee its completeness or accuracy as it is based on data received from sources outside our company.

Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/20/06	1.0	Initial release.
7/05/06	1.1	100% Material Declaration.
10/5/06	1.2	Updated component descriptions.